

microQSFP Connector

1. SCOPE

1.1. Content

This specification defines performance, test and quality requirements for the microQSFP Connector

1.2. Qualification

When tests are performed on the subject product line, procedures specified in Figure 1 shall be used. All inspections shall be performed using the applicable inspection plan and product drawing.

1.3. Qualification Test Results

Successful qualification testing on the subject product line was completed on 02MAY2017. The Qualification Test Report number is 501-134065. This documentation is available from Engineering Practices and Standards (EPS).

2. APPLICABLE DOCUMENTS AND FORMS

The following documents and forms constitute a part of this specification to the extent specified herein. Unless otherwise indicated, the latest edition of the document applies. In the event of conflict between the requirements of the specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the reference documents, this specification shall take precedence.

2.1. TE Documents

- ◆ 114-32142 Application Specification
- ◆ 501-134065 Qualification Test Report

2.2. Industry Documents

- ◆ EIA-364 Electrical Connector/Socket Test Procedures Including Environmental Classifications
- ◆ J-STD-002 Surface Mount Solderability

2.3. Reference Document

- ◆ 109-197 Test Specification (TE Test Specification vs EIA and IEC Test Methods)

3. REQUIREMENTS

3.1. Design and Construction

Product shall be of the design, construction, materials and physical dimensions specified on the applicable product drawing.

3.2. Ratings

Voltage	Current	Temperature
30 VDC	Signal Application Only	-55 to 85°C

3.3. Test Requirements and Procedures Summary

Unless otherwise specified, all tests shall be performed at ambient environmental conditions.

Test Description	Requirement	Procedure
Initial examination of product	Meets requirements of product drawing.	EIA-364-18. Visual examination and dimensional (C of C) inspection per product drawing.
Final examination of product	Meets visual requirements.	EIA-364-18. Visual examination.
ELECTRICAL		
Low Level Contact Resistance (LLCR)	ΔR 10 m Ω maximum	EIA-364-23. Max. open voltage 20mV. Max current 100 mA DC. All contacts to be measured.
Insulation resistance	1000 M Ω minimum	EIA-364-21. Test voltage 100V DC. Duration: 1 minute. Measure between adjacent signal contacts.
Withstanding voltage	No breakdown or flashover.	EIA-364-20, Condition I. Test voltage: 300 volts AC at sea level. Test between adjacent contacts, signal to signal and signal to ground
MECHANICAL		
Random vibration	No discontinuity > 1 microsecond See Note.	EIA-364-28, Test Condition VII, Test Condition Letter D. Subject mated specimens to 3.10 G RMS between 20 to 500 Hz. Fifteen minutes in each of 3 mutually perpendicular planes.
Mechanical shock	No discontinuity > 1 microsecond See Note.	EIA-364-27, Test Condition H. Subject mated specimens to 30 Gs half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction applied along 3 mutually perpendicular planes, 18 total shocks.
Durability	See Note.	EIA-364-9. Mate and un-mate specimens. Disable latch. Operation cycles: 200, 100 cycles per mating pcb. Swap out pcb after 100 cycles. Continue 100 cycles with second pcb re-insert 1st pcb for LLCR
ENVIRONMENTAL		
Solderability	95% minimum wetting	IPC/ECA J-STD-002, Test S1 Preheat: 150° to 180°C / 60-120 seconds Reflow: 230° to 260°C / 30-60 second
Resistance to reflow soldering heat	See Note.	TEC-109-201 Method-A, Condition-B. Subject SMD connector to 3x reflow curve 260°C peak.
Thermal shock.	See Note.	EIA-364-32, Method A, Test Condition I. Subject mated specimens to 5 cycles between -55° and 85°C with 30 minute dwells at temperature extremes and 1 minute transition between temperatures.
Humidity/temperature cycling.	See Note.	EIA-364-31, Method IV. Subject mated specimens to 10 cycles (10 days) between 25 and 65°C at 80 to 100% RH.
Temperature life.	See Note.	EIA-364-17, Method A, Test Subject mated specimens to 85°C for 250 hours.

Figure 1 cont.

Test Description	Requirement	Procedure
Mixed flowing gas.	See Note.	EIA-364-65, Class IIA (4 gas). Subject board mounted specimens to environmental Class IIA for 14 days. One-half of the specimens (receptacle only) unmated for 7 days followed by 7 days mated. The remaining one-half of the specimens mated for 14 days.
Thermal cycling	See Note.	EIA-364-110, Condition A. Subject mated and board mounted specimens to 10 temperature cycles between 15 ±3°C and 85 ±3°C as measured on the specimen. Ramp times > 2°C per minute with dwell times long enough to ensure contacts reach the temperature extremes (5 minutes minimum). Humidity not controlled.
Minute disturbance	See Note.	Manually un-mate and mate the specimen 5 times.



NOTE

Shall meet visual requirements, show no physical damage, and meet requirements of additional tests as specified in the Product Qualification and Requalification Test Sequence shown in Figure 2.

Figure 1 end

3.4. Product Qualification and Requalification Test Sequence

Test or Examination	Test Group (a)					
	1	2	3	4	5	6
	Test Sequence (b)					
Initial examination of product	1	1	1	1	1	1
Low Level Contact Resistance	3,5,9	3,6	3,6,9			
Insulation resistance				2,6		
Withstanding voltage				3,7		
Random vibration	6					
Mechanical shock	7					
Durability	4(c)					
Solderability						2
Resistance to reflow soldering heat					2	
Thermal shock				4		
Humidity/temperature cycling				5		
Temperature life		4				
Mixed flowing gas			4			
Thermal cycling			7			
Minute disturbance	2,8	2,5	2,5,8			
Final examination of product	10	7	10	8	3	3

Figure 2



NOTE

- (a) Samples shall be selected at random from current production. Unless otherwise specified, all test groups shall consist of a minimum of 5 connectors of which all contacts shall be tested.
- (b) Numbers indicate sequence in which tests are performed.
- (c) Measure LLCR after 100 cycles, replace module and add 100 cycles, re-insert original module, measure LLCR